

# MOSFET

## OptiMOS™ Power-MOSFET, 40 V

### Features

- Optimized for high performance SMPS, e.g. sync. rec.
- Very low on-resistance  $R_{DS(on)}$  @  $V_{GS}=4.5\text{ V}$
- 100% avalanche tested
- Superior thermal resistance
- N-channel
- Qualified according to JEDEC<sup>1)</sup> for target applications
- Pb-free lead plating; RoHS compliant
- Halogen-free according to IEC61249-2-21

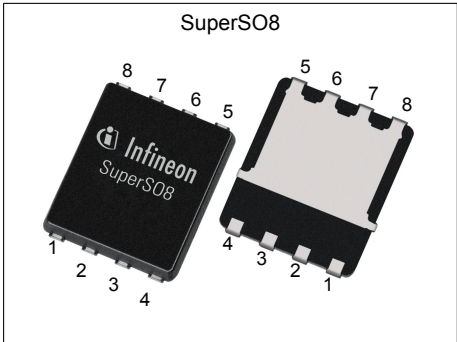
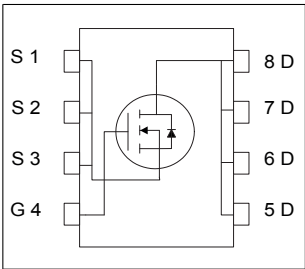


Table 1 Key Performance Parameters

| Parameter        | Value | Unit |
|------------------|-------|------|
| $V_{DS}$         | 40    | V    |
| $R_{DS(on),max}$ | 2.6   | mΩ   |
| $I_D$            | 119   | A    |
| $Q_{OSS}$        | 28    | nC   |
| $Q_G(0V..10V)$   | 32    | nC   |



RoHS

| Type / Ordering Code | Package    | Marking  | Related Links |
|----------------------|------------|----------|---------------|
| BSC026N04LS          | PG-TDSON-8 | 026N04LS | -             |

<sup>1)</sup> J-STD20 and JESD22

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## 1 Maximum ratings

at  $T_A=25\text{ °C}$ , unless otherwise specified

**Table 2 Maximum ratings**

| Parameter                                    | Symbol            | Values |      |                              | Unit | Note / Test Condition                                                                                                                                                                                                                                           |
|----------------------------------------------|-------------------|--------|------|------------------------------|------|-----------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------|
|                                              |                   | Min.   | Typ. | Max.                         |      |                                                                                                                                                                                                                                                                 |
| Continuous drain current <sup>1)</sup>       | $I_D$             | -      | -    | 119<br>75<br>101<br>64<br>23 | A    | $V_{GS}=10\text{ V}$ , $T_C=25\text{ °C}$<br>$V_{GS}=10\text{ V}$ , $T_C=100\text{ °C}$<br>$V_{GS}=4.5\text{ V}$ , $T_C=25\text{ °C}$<br>$V_{GS}=4.5\text{ V}$ , $T_C=100\text{ °C}$<br>$V_{GS}=10\text{ V}$ , $T_A=25\text{ °C}$ , $R_{thJA}=50\text{ K/W}^2)$ |
| Pulsed drain current <sup>3)</sup>           | $I_{D,pulse}$     | -      | -    | 476                          | A    | $T_C=25\text{ °C}$                                                                                                                                                                                                                                              |
| Avalanche energy, single pulse <sup>4)</sup> | $E_{AS}$          | -      | -    | 50                           | mJ   | $I_D=50\text{ A}$ , $R_{GS}=25\text{ }\Omega$                                                                                                                                                                                                                   |
| Gate source voltage                          | $V_{GS}$          | -20    | -    | 20                           | V    | -                                                                                                                                                                                                                                                               |
| Power dissipation                            | $P_{tot}$         | -      | -    | 63<br>2.5                    | W    | $T_C=25\text{ °C}$<br>$T_A=25\text{ °C}$ , $R_{thJA}=50\text{ K/W}^2)$                                                                                                                                                                                          |
| Operating and storage temperature            | $T_j$ , $T_{stg}$ | -55    | -    | 150                          | °C   | IEC climatic category;<br>DIN IEC 68-1: 55/150/56                                                                                                                                                                                                               |

## 2 Thermal characteristics

**Table 3 Thermal characteristics**

| Parameter                                                   | Symbol     | Values |      |      | Unit | Note / Test Condition |
|-------------------------------------------------------------|------------|--------|------|------|------|-----------------------|
|                                                             |            | Min.   | Typ. | Max. |      |                       |
| Thermal resistance, junction - case, bottom                 | $R_{thJC}$ | -      | 1.2  | 2    | K/W  | -                     |
| Thermal resistance, junction - case, top                    | $R_{thJC}$ | -      | -    | 20   | K/W  | -                     |
| Device on PCB, 6 cm <sup>2</sup> cooling area <sup>2)</sup> | $R_{thJA}$ | -      | -    | 50   | K/W  | -                     |

<sup>1)</sup> Rating refers to the product only with datasheet specified absolute maximum values, maintaining case temperature at 25°C. For higher case temperature please refer to Diagram 2. De-rating will be required based on the actual environmental conditions.

<sup>2)</sup> Device on 40 mm x 40 mm x 1.5 mm epoxy PCB FR4 with 6 cm<sup>2</sup> (one layer, 70 µm thick) copper area for drain connection. PCB is vertical in still air.

<sup>3)</sup> See Diagram 3 for more detailed information

<sup>4)</sup> See Diagram 13 for more detailed information

### 3 Electrical characteristics

at  $T_j=25\text{ °C}$ , unless otherwise specified

**Table 4 Static characteristics**

| Parameter                        | Symbol        | Values |            |            | Unit          | Note / Test Condition                                                                                                               |
|----------------------------------|---------------|--------|------------|------------|---------------|-------------------------------------------------------------------------------------------------------------------------------------|
|                                  |               | Min.   | Typ.       | Max.       |               |                                                                                                                                     |
| Drain-source breakdown voltage   | $V_{(BR)DSS}$ | 40     | -          | -          | V             | $V_{GS}=0\text{ V}$ , $I_D=1\text{ mA}$                                                                                             |
| Gate threshold voltage           | $V_{GS(th)}$  | 1.2    | -          | 2          | V             | $V_{DS}=V_{GS}$ , $I_D=250\text{ }\mu\text{A}$                                                                                      |
| Zero gate voltage drain current  | $I_{DSS}$     | -      | 0.1<br>10  | 1<br>100   | $\mu\text{A}$ | $V_{DS}=40\text{ V}$ , $V_{GS}=0\text{ V}$ , $T_j=25\text{ °C}$<br>$V_{DS}=40\text{ V}$ , $V_{GS}=0\text{ V}$ , $T_j=125\text{ °C}$ |
| Gate-source leakage current      | $I_{GSS}$     | -      | 10         | 100        | nA            | $V_{GS}=20\text{ V}$ , $V_{DS}=0\text{ V}$                                                                                          |
| Drain-source on-state resistance | $R_{DS(on)}$  | -      | 2.1<br>2.6 | 2.6<br>3.6 | m $\Omega$    | $V_{GS}=10\text{ V}$ , $I_D=50\text{ A}$<br>$V_{GS}=4.5\text{ V}$ , $I_D=50\text{ A}$                                               |
| Gate resistance <sup>1)</sup>    | $R_G$         | -      | 0.9        | 1.8        | $\Omega$      | -                                                                                                                                   |
| Transconductance                 | $g_{fs}$      | 85     | 170        | -          | S             | $ V_{DS} >2 I_D R_{DS(on)max}$ , $I_D=50\text{ A}$                                                                                  |

**Table 5 Dynamic characteristics**

| Parameter                                  | Symbol       | Values |      |      | Unit | Note / Test Condition                                                                              |
|--------------------------------------------|--------------|--------|------|------|------|----------------------------------------------------------------------------------------------------|
|                                            |              | Min.   | Typ. | Max. |      |                                                                                                    |
| Input capacitance <sup>1)</sup>            | $C_{iss}$    | -      | 2300 | 3220 | pF   | $V_{GS}=0\text{ V}$ , $V_{DS}=20\text{ V}$ , $f=1\text{ MHz}$                                      |
| Output capacitance <sup>1)</sup>           | $C_{oss}$    | -      | 640  | 900  | pF   | $V_{GS}=0\text{ V}$ , $V_{DS}=20\text{ V}$ , $f=1\text{ MHz}$                                      |
| Reverse transfer capacitance <sup>1)</sup> | $C_{rss}$    | -      | 52   | 104  | pF   | $V_{GS}=0\text{ V}$ , $V_{DS}=20\text{ V}$ , $f=1\text{ MHz}$                                      |
| Turn-on delay time                         | $t_{d(on)}$  | -      | 5    | -    | ns   | $V_{DD}=20\text{ V}$ , $V_{GS}=10\text{ V}$ , $I_D=50\text{ A}$ ,<br>$R_{G,ext}=1.6\text{ }\Omega$ |
| Rise time                                  | $t_r$        | -      | 4    | -    | ns   | $V_{DD}=20\text{ V}$ , $V_{GS}=10\text{ V}$ , $I_D=50\text{ A}$ ,<br>$R_{G,ext}=1.6\text{ }\Omega$ |
| Turn-off delay time                        | $t_{d(off)}$ | -      | 37   | -    | ns   | $V_{DD}=20\text{ V}$ , $V_{GS}=10\text{ V}$ , $I_D=50\text{ A}$ ,<br>$R_{G,ext}=1.6\text{ }\Omega$ |
| Fall time                                  | $t_f$        | -      | 4    | -    | ns   | $V_{DD}=20\text{ V}$ , $V_{GS}=10\text{ V}$ , $I_D=50\text{ A}$ ,<br>$R_{G,ext}=1.6\text{ }\Omega$ |

**Table 6 Gate charge characteristics<sup>2)</sup>**

| Parameter                          | Symbol        | Values |      |      | Unit | Note / Test Condition                                                        |
|------------------------------------|---------------|--------|------|------|------|------------------------------------------------------------------------------|
|                                    |               | Min.   | Typ. | Max. |      |                                                                              |
| Gate to source charge              | $Q_{gs}$      | -      | 6.0  | -    | nC   | $V_{DD}=20\text{ V}$ , $I_D=50\text{ A}$ , $V_{GS}=0\text{ to }10\text{ V}$  |
| Gate charge at threshold           | $Q_{g(th)}$   | -      | 3.6  | -    | nC   | $V_{DD}=20\text{ V}$ , $I_D=50\text{ A}$ , $V_{GS}=0\text{ to }10\text{ V}$  |
| Gate to drain charge <sup>1)</sup> | $Q_{gd}$      | -      | 5.2  | 7.3  | nC   | $V_{DD}=20\text{ V}$ , $I_D=50\text{ A}$ , $V_{GS}=0\text{ to }10\text{ V}$  |
| Switching charge                   | $Q_{sw}$      | -      | 7.5  | -    | nC   | $V_{DD}=20\text{ V}$ , $I_D=50\text{ A}$ , $V_{GS}=0\text{ to }10\text{ V}$  |
| Gate charge total <sup>1)</sup>    | $Q_g$         | -      | 32   | 45   | nC   | $V_{DD}=20\text{ V}$ , $I_D=50\text{ A}$ , $V_{GS}=0\text{ to }10\text{ V}$  |
| Gate plateau voltage               | $V_{plateau}$ | -      | 2.6  | -    | V    | $V_{DD}=20\text{ V}$ , $I_D=50\text{ A}$ , $V_{GS}=0\text{ to }10\text{ V}$  |
| Gate charge total <sup>1)</sup>    | $Q_g$         | -      | 16   | 22   | nC   | $V_{DD}=20\text{ V}$ , $I_D=50\text{ A}$ , $V_{GS}=0\text{ to }4.5\text{ V}$ |
| Gate charge total, sync. FET       | $Q_{g(sync)}$ | -      | 13   | -    | nC   | $V_{DS}=0.1\text{ V}$ , $V_{GS}=0\text{ to }4.5\text{ V}$                    |
| Output charge <sup>1)</sup>        | $Q_{oss}$     | -      | 28   | 39   | nC   | $V_{DD}=20\text{ V}$ , $V_{GS}=0\text{ V}$                                   |

<sup>1)</sup> Defined by design. Not subject to production test

<sup>2)</sup> See "Gate charge waveforms" for parameter definition

**Table 7 Reverse diode**

| Parameter                           | Symbol        | Values |      |      | Unit | Note / Test Condition                                                      |
|-------------------------------------|---------------|--------|------|------|------|----------------------------------------------------------------------------|
|                                     |               | Min.   | Typ. | Max. |      |                                                                            |
| Diode continuous forward current    | $I_S$         | -      | -    | 63   | A    | $T_C=25\text{ °C}$                                                         |
| Diode pulse current                 | $I_{S,pulse}$ | -      | -    | 476  | A    | $T_C=25\text{ °C}$                                                         |
| Diode forward voltage               | $V_{SD}$      | -      | 0.86 | 1    | V    | $V_{GS}=0\text{ V}$ , $I_F=50\text{ A}$ , $T_j=25\text{ °C}$               |
| Reverse recovery time <sup>1)</sup> | $t_{rr}$      | -      | 24   | 48   | ns   | $V_R=20\text{ V}$ , $I_F=50\text{ A}$ , $di_F/dt=400\text{ A/}\mu\text{s}$ |
| Reverse recovery charge             | $Q_{rr}$      | -      | 57   | -    | nC   | $V_R=20\text{ V}$ , $I_F=50\text{ A}$ , $di_F/dt=400\text{ A/}\mu\text{s}$ |

<sup>1)</sup> Defined by design. Not subject to production test

## 4 Electrical characteristics diagrams

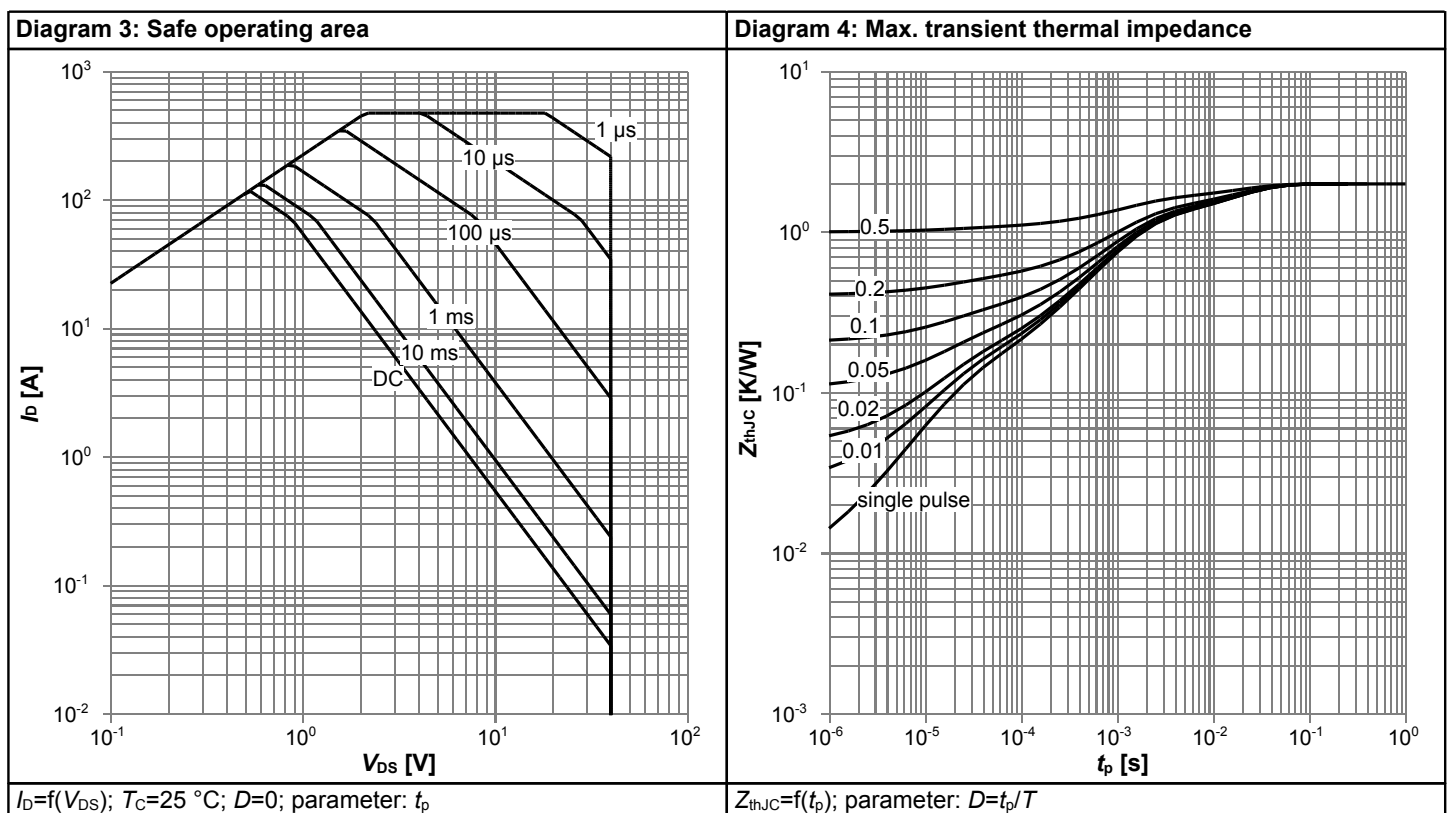
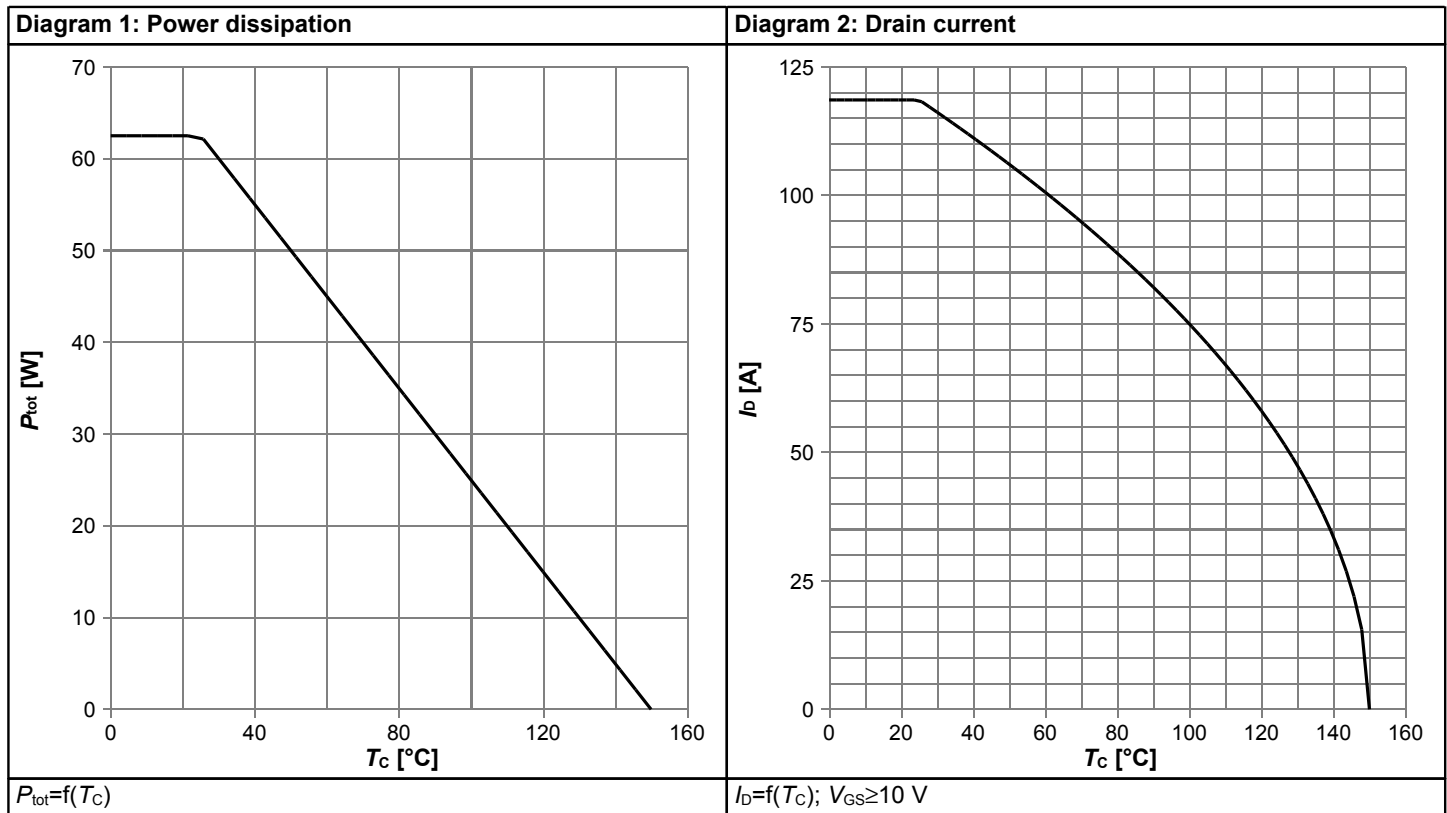
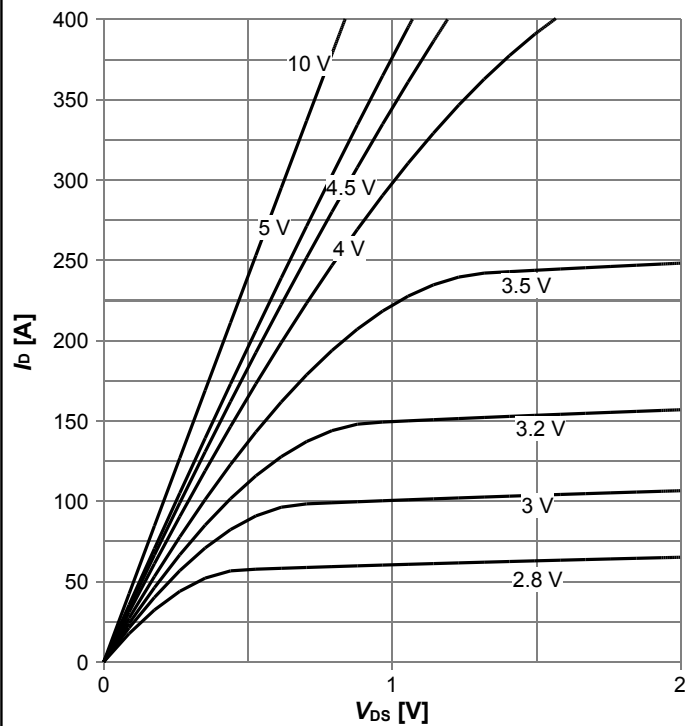
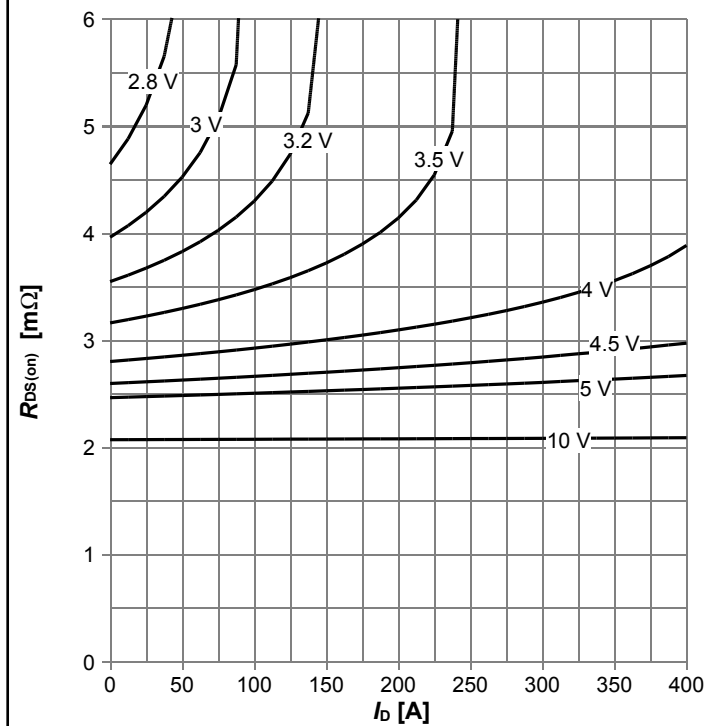


Diagram 5: Typ. output characteristics



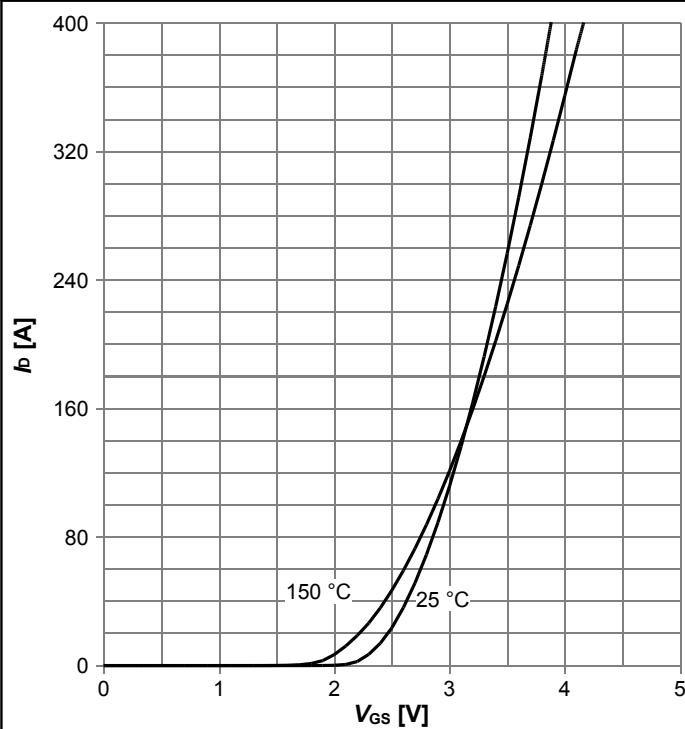
$I_D = f(V_{DS})$ ;  $T_j = 25^\circ\text{C}$ ; parameter:  $V_{GS}$

Diagram 6: Typ. drain-source on resistance



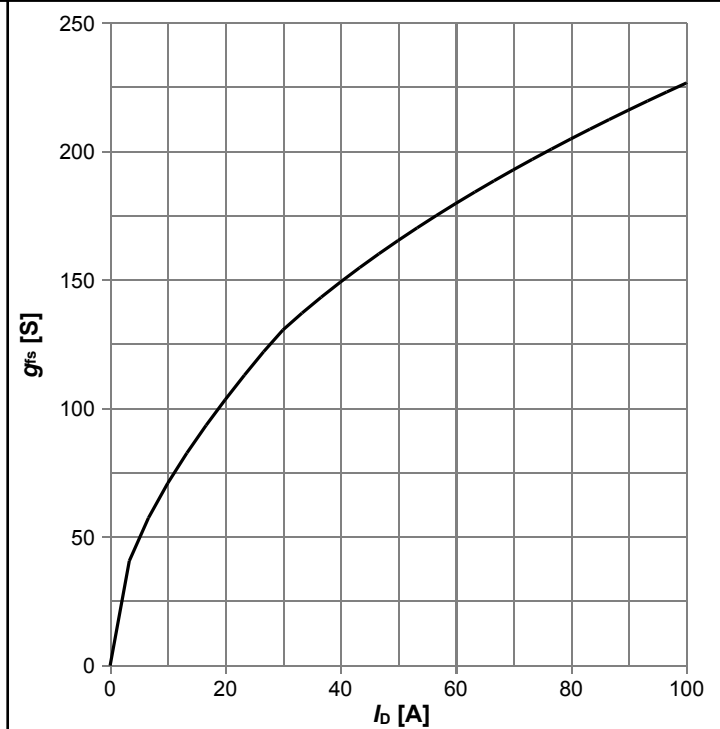
$R_{DS(on)} = f(I_D)$ ;  $T_j = 25^\circ\text{C}$ ; parameter:  $V_{GS}$

Diagram 7: Typ. transfer characteristics



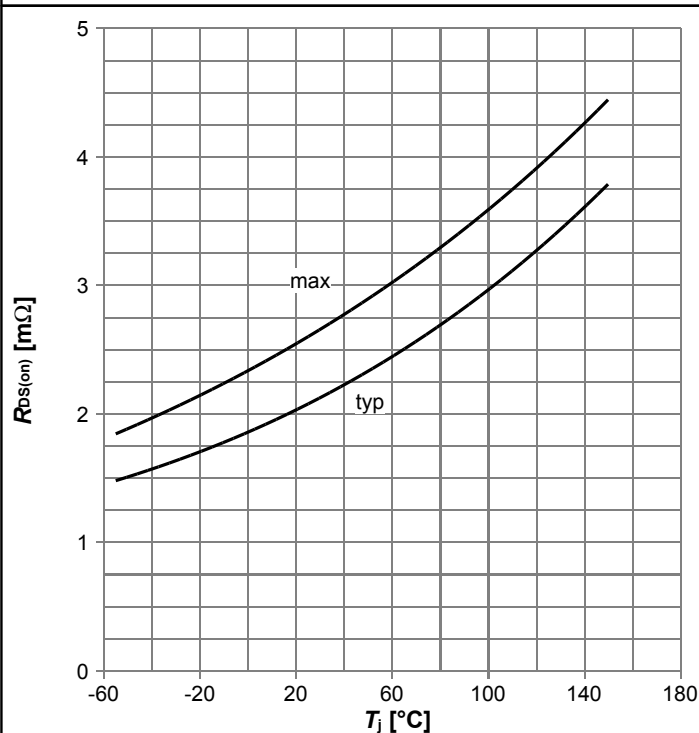
$I_D = f(V_{GS})$ ;  $|V_{DS}| > 2|I_D|R_{DS(on)max}$ ; parameter:  $T_j$

Diagram 8: Typ. forward transconductance



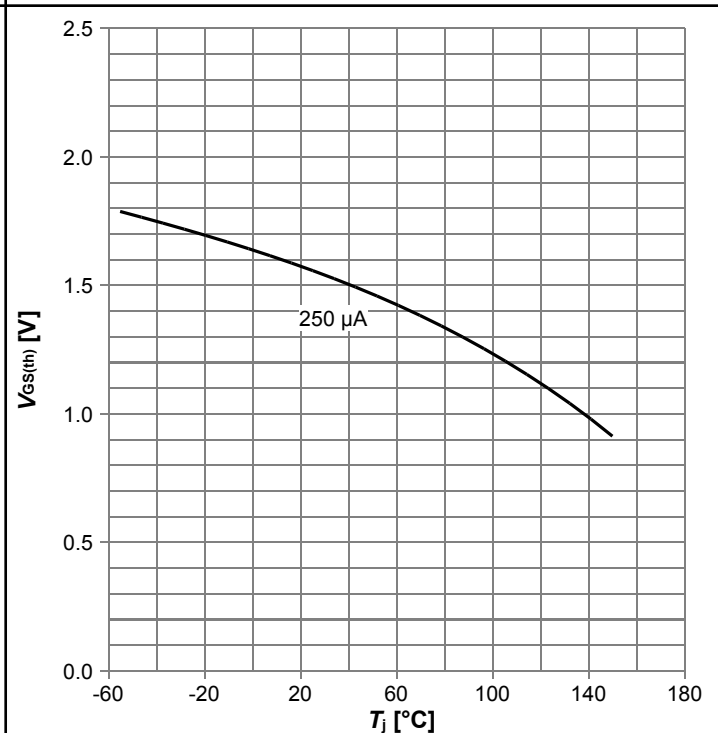
$g_{fs} = f(I_D)$ ;  $T_j = 25^\circ\text{C}$

Diagram 9: Drain-source on-state resistance



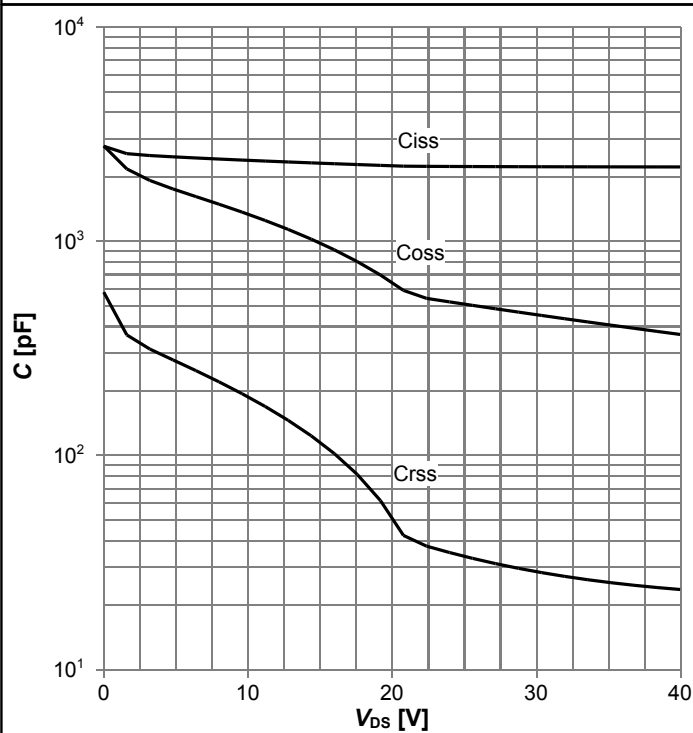
$R_{DS(on)} = f(T_j)$ ;  $I_D = 50$  A;  $V_{GS} = 10$  V

Diagram 10: Typ. gate threshold voltage



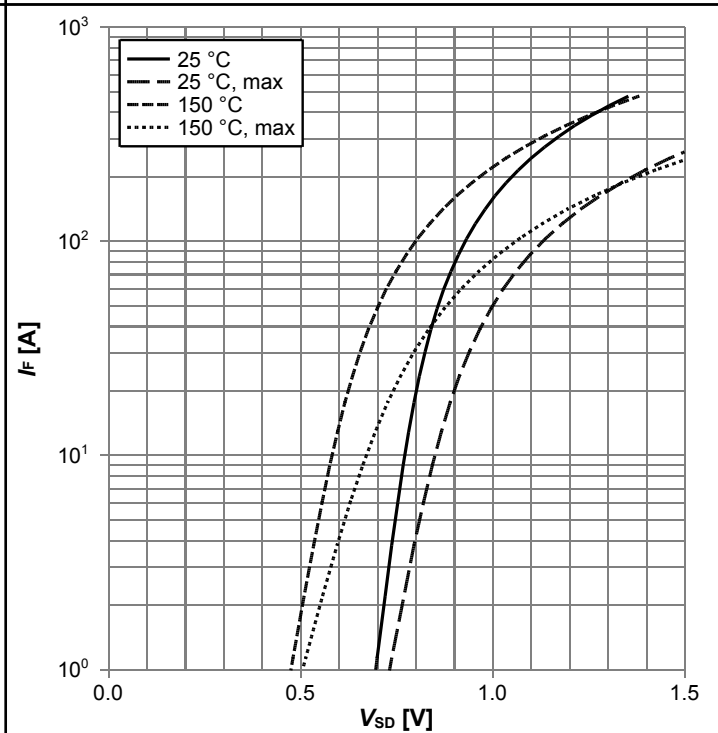
$V_{GS(th)} = f(T_j)$ ;  $V_{GS} = V_{DS}$ ;  $I_D = 250$  μA

Diagram 11: Typ. capacitances



$C = f(V_{DS})$ ;  $V_{GS} = 0$  V;  $f = 1$  MHz

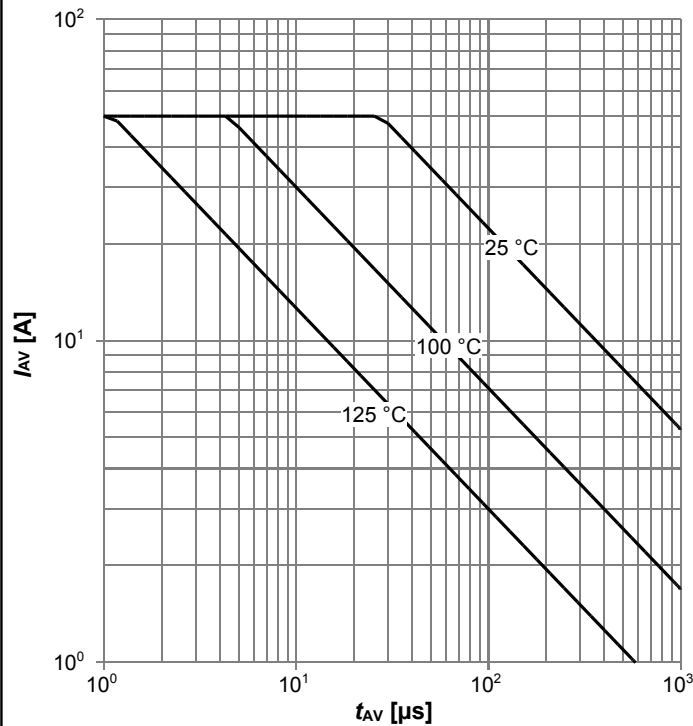
Diagram 12: Forward characteristics of reverse diode



$I_F = f(V_{SD})$ ; parameter:  $T_j$

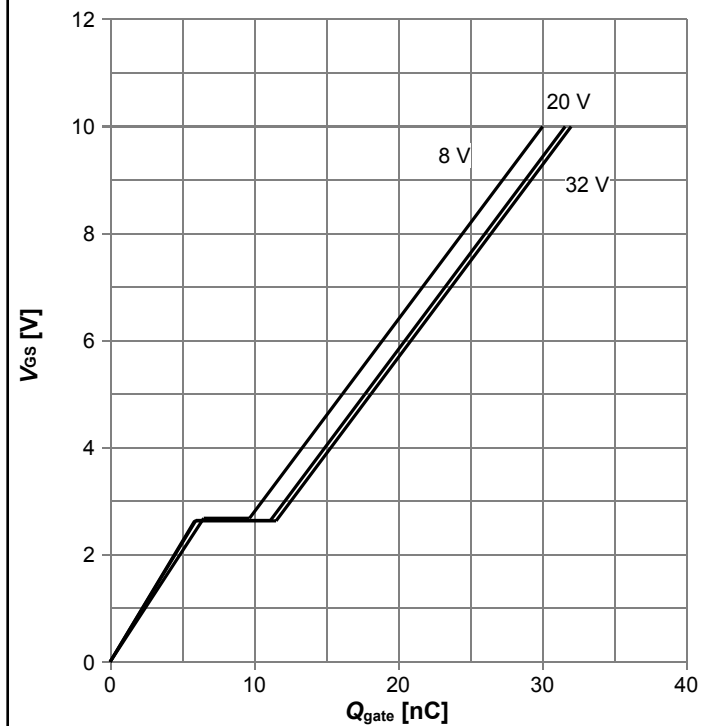


Diagram 13: Avalanche characteristics



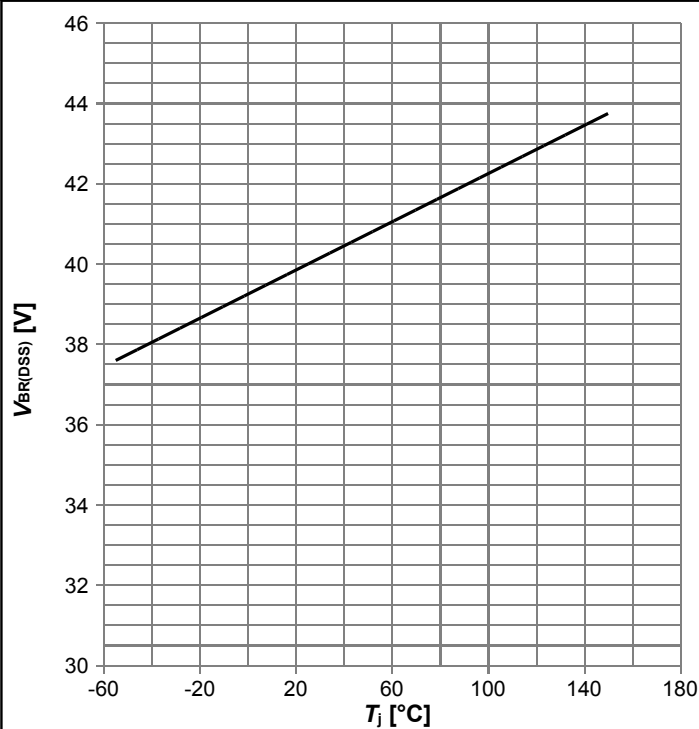
$I_{AS}=f(t_{AV})$ ;  $R_{GS}=25\ \Omega$ ; parameter:  $T_{j(start)}$

Diagram 14: Typ. gate charge



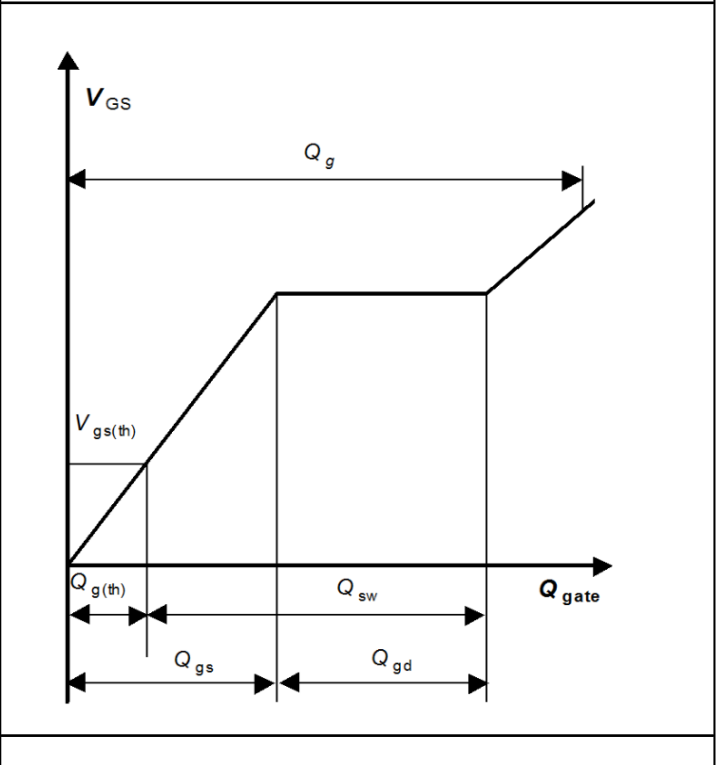
$V_{GS}=f(Q_{gate})$ ;  $I_D=50\text{ A}$  pulsed; parameter:  $V_{DD}$

Diagram 15: Drain-source breakdown voltage

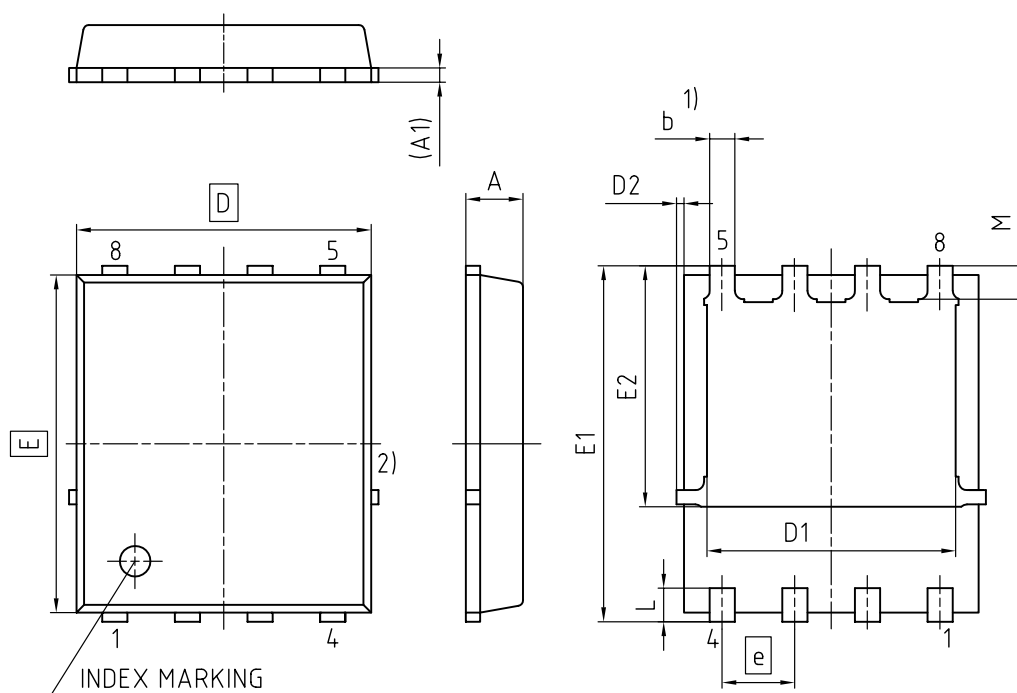


$V_{BR(DSS)}=f(T_j)$ ;  $I_D=1\text{ mA}$

Diagram Gate charge waveforms



## 5 Package Outlines



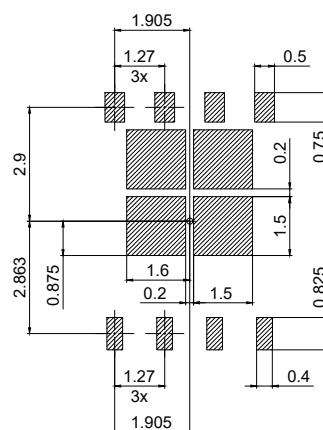
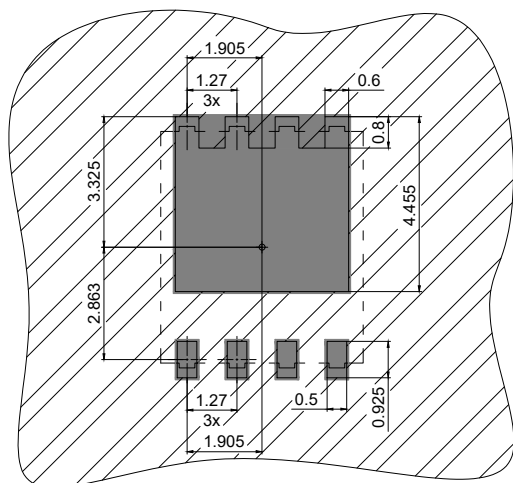
- 1) EXCLUDING MOLD FLASH  
2) REMOVAL ON MOLD GATE  
INTRUSION 0.1 MM  
PROTRUSION 0.1 MM  
LEAD LENGTH UP TO ANTI FLASH LINE  
ALL METAL SURFACES ARE PLATED, EXCEPT AREA OF CUT

| DIMENSION | MILLIMETERS |      |
|-----------|-------------|------|
|           | MIN.        | MAX. |
| A         | 0.90        | 1.20 |
| A1        | 0.15        | 0.35 |
| b         | 0.34        | 0.54 |
| D         | 4.80        | 5.35 |
| D1        | 3.90        | 4.40 |
| D2        | 0.03        | 0.23 |
| E         | 5.70        | 6.10 |
| E1        | 5.90        | 6.42 |
| E2        | 3.88        | 4.31 |
| e         | 1.27        |      |
| L         | 0.45        | 0.71 |
| M         | 0.45        | 0.69 |

|                             |
|-----------------------------|
| DOCUMENT NO.<br>Z8B00003332 |
| REVISION<br>07              |
| SCALE 10:1<br>0 1 2 3mm     |
| EUROPEAN PROJECTION<br>     |
| ISSUE DATE<br>06.06.2019    |

Figure 1 Outline PG-TDSON-8, dimensions in mm

# PG-TDSON-8: Recommended Boardpads & Apertures



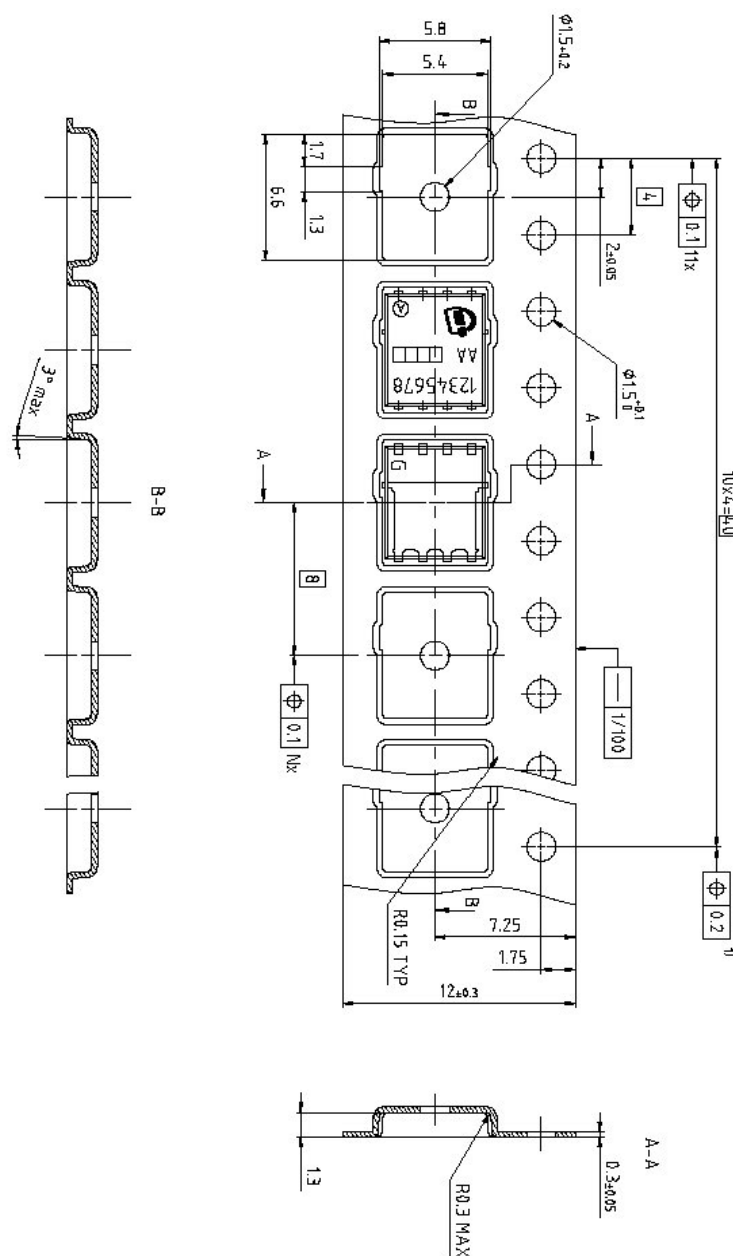
■ copper

▨ solder mask

▨ stencil apertures

all dimensions in mm

Figure 2 Outline Boardpads (TDSON-8), dimensions in mm



Dimension in mm

Figure 3 Outline Tape (TDSON-8)

## Revision History

BSC026N04LS

Revision: 2020-08-18, Rev. 2.3

### Previous Revision

| Revision | Date       | Subjects (major changes since last revision) |
|----------|------------|----------------------------------------------|
| 2.1      | 2016-06-09 | Update footnotes and max values              |
| 2.2      | 2020-03-26 | Update package drawings                      |
| 2.3      | 2020-08-18 | Update current rating                        |

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